

Thosolute Muximum Rutings (10 - 2	25 (C)			
Item	Symbol	Ratings	Unit 250-00	
Collector to base voltage	V _{CBO}	20	V	
Collector to emitter voltage	V _{CEO}	11	V	
Emitter to base voltage	V _{EBO}	3	V	
Collector current	Ι _c	50	mA	
Collector power dissipation	Pc	150	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	



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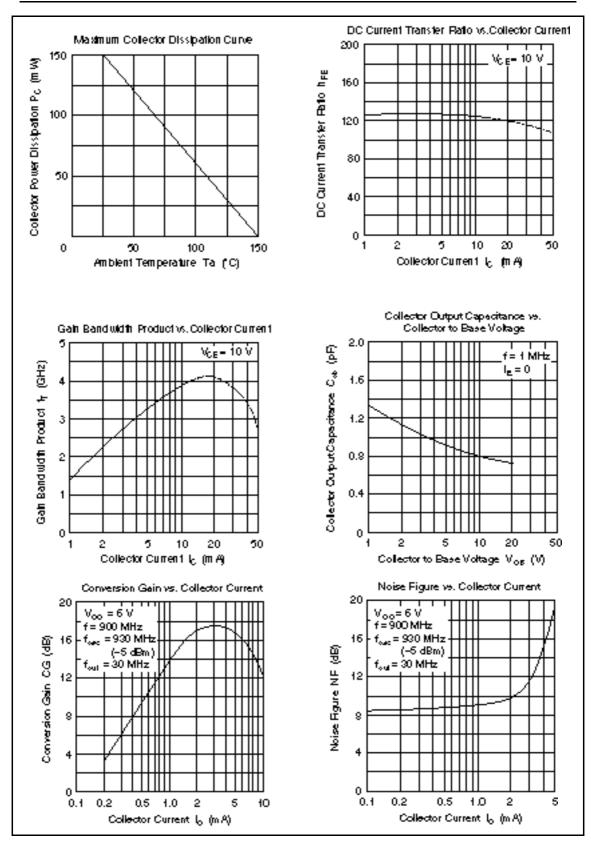
Electrical Characteristics (Ta = 25° C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	20	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	11	_	_	V	$I_c = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	3	_	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}			0.5	μA	$V_{CB} = 15 \text{ V}, \text{ I}_{E} = 0$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	_	0.7	V	$I_{c} = 10 \text{ mA}, I_{B} = 5 \text{ mA}$
DC current transfer ratio	h_{FE}	45	_	200		$V_{ce} = 10 \text{ V}, \text{ I}_{c} = 5 \text{ mA}$
Gain bandwidth product	f _T	2.5	3.8	—	GHz	$V_{ce} = 10 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Collector output capacitance	Cob	_	0.8	1.5	pF	$V_{_{CB}} = 10 \text{ V}, \text{ I}_{_{E}} = 0, \text{ f} = 1 \text{ MHz}$
Conversion gain	CG	10	14	_	dB	$V_{cc} = 10 \text{ V}, \text{ I}_{c} = 1 \text{ mA},$ f = 900 MHz,
Noise figure	NF		10	14	dB	$f_{osc} = 930 \text{ MHz}, (-5 \text{dBm}),$ $f_{out} = 30 \text{ MHz}$

Note: Marking is "DI-"

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